

HVM14SR

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0114-0400Z
(Previous: ADE-208-084C)
Rev.4.00
Oct.08.2003

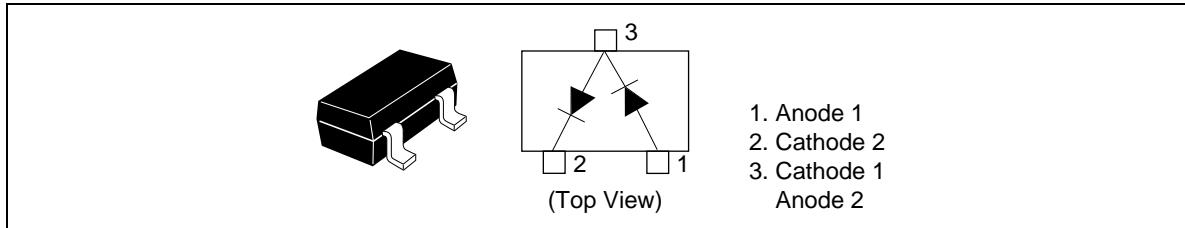
Features

- Low forward resistance. ($r_f = 7.0 \Omega$ max)
- Low capacitance. ($C = 0.25 \text{ pF}$ typ)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVM14SR	H7	MPAK

Pin Arrangement



HVM14SR

Absolute Maximum Ratings ^{*1}

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	50	V
Forward current	I _F	50	mA
Power dissipation	P _d	100	mW
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	−55 to +125	°C

Note: 1. Absolute maximum ratings are described each unit separately.

Electrical Characteristics ^{*1}

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V _F	—	—	1.0	V	I _F = 50 mA
Reverse current	I _R	—	—	100	nA	V _R = 50 V
Capacitance	C	—	0.25	—	pF	V _R = 50 V, f = 1 MHz
Forward resistance	r _f	—	—	7.0	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability ^{*2}	—	200	—	—	V	C = 200 pF, Both forward and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion; I_R ≥ 200 nA at V_R = 50 V

Main Characteristic

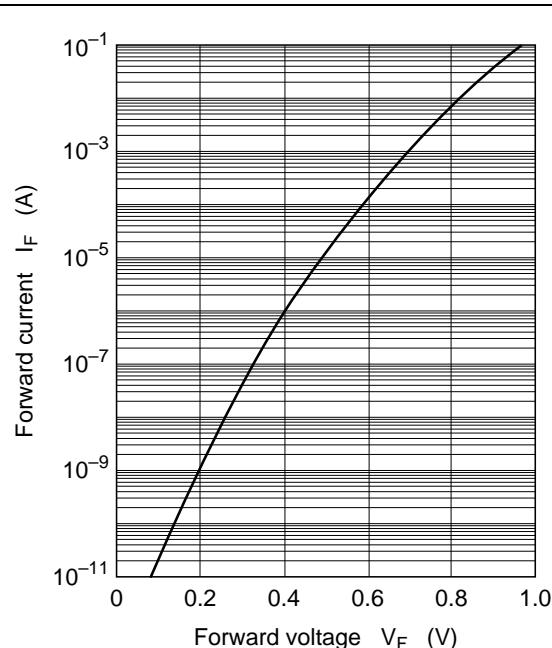


Fig.1 Forward current vs. Forward voltage

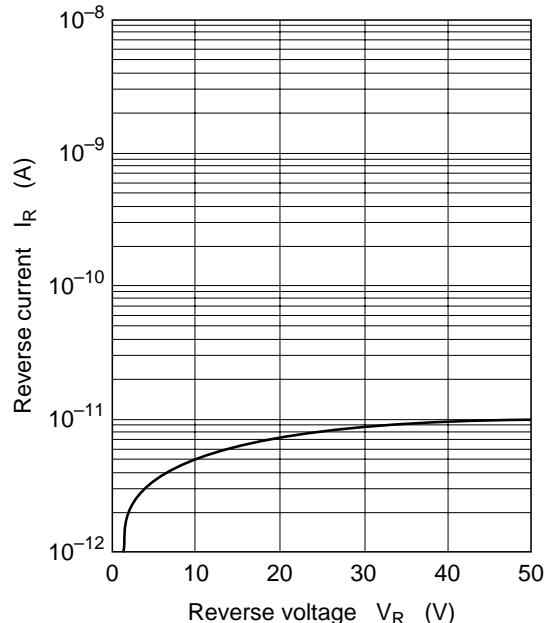


Fig.2 Reverse current vs. Reverse voltage

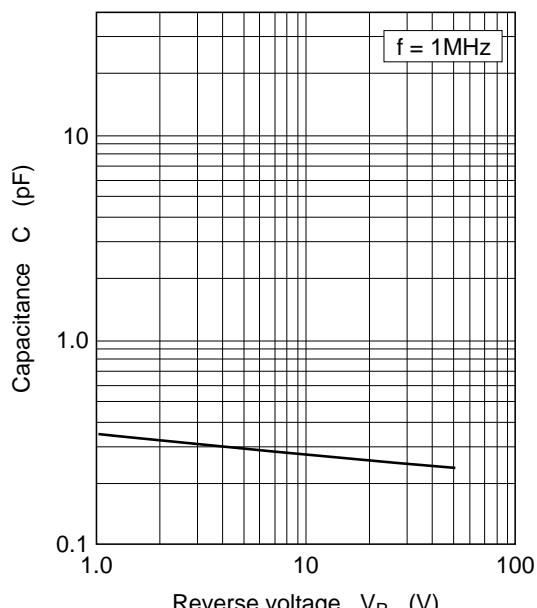


Fig.3 Capacitance vs. Reverse voltage

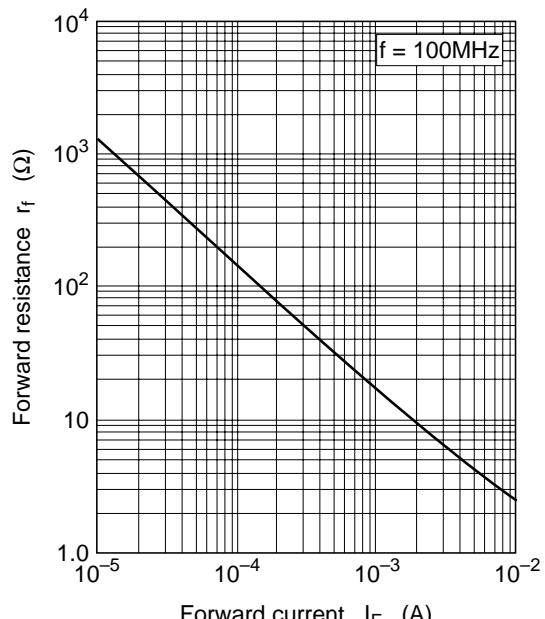
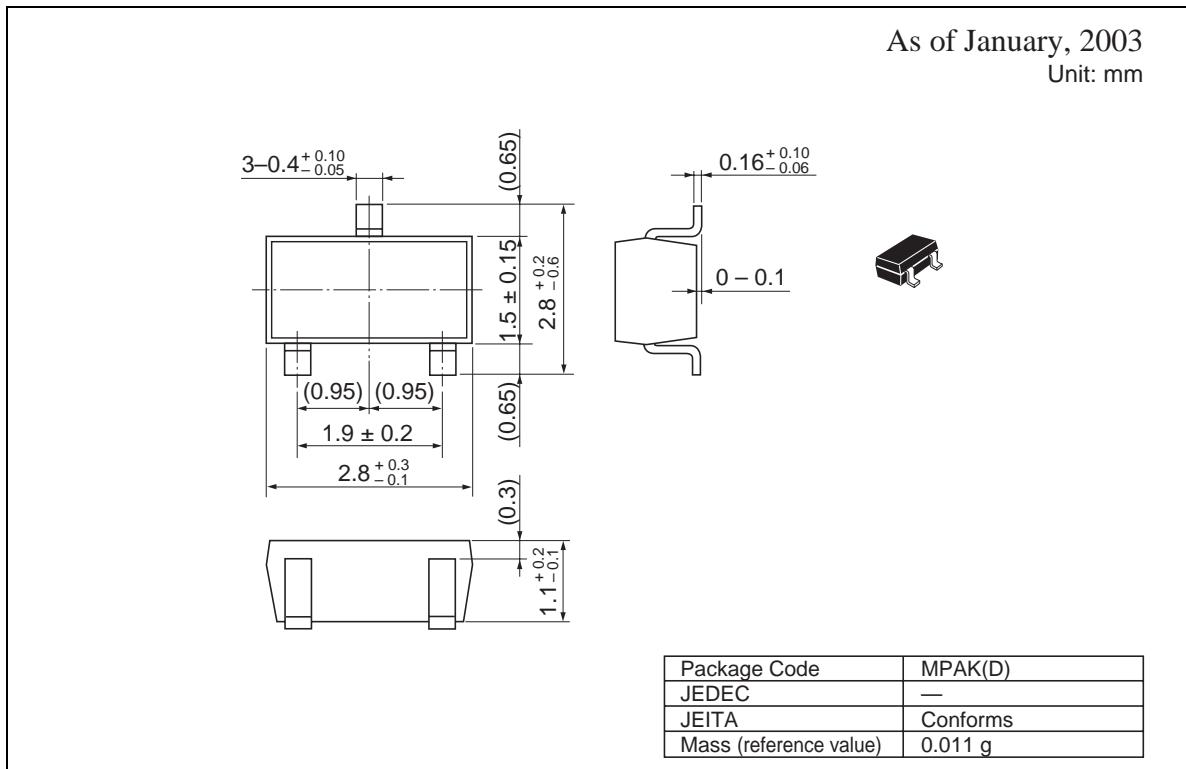


Fig.4 Forward resistance vs. Forward current

Package Dimensions



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